NXP

Final Product Change Notification | 201309007F01

Issue Date: 16-Sep-2013
Effective Date: 14-Dec-2013
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Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online

QUALITY

Management Summary

Outsourcing of plating process for DIP packages from APB (NXP Semiconductors Bangkok) to our subcontractor Lentus (Bangkok).

Change Category

[ ] Wafer Fab process	[X] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[X] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[X] Assembly Location	[ ] Test Location	[ ] Packing/Shipping/Labeling

Transfer plating process for DIP packages from APB (NXP Bangkok) to Lentus (Bangkok)

Details of this Change

The deflash and plating processes for all products in tin (Sn100) plated DIP packages will become outsourced from APB (NXP Semiconductors Assembly Plant Bangkok) to our subcontractor Lentus (Bangkok). In this change the plating will change from bright to the world standard of matte plating. All other processes will remain in APB.
The release results report is attached to this notification.

Why do we Implement this Change

NXP implements this transfer to improve production efficiency.

Identification of Affected Products

Products can be identified by the weekcode printed on the label and marked on the products. From wk 1350 all plating will be done at Lentus.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 18-Dec-2013

Impact

no impact to the product's functionality anticipated.
- Electrical and mechanical and thermal parameters of products will not change.
- No impact on form, fit, function, quality or reliability.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information:
Self qualification _____

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 16-Oct-2013.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of $4.36 billion in 2012.

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